

General Description

The WSC4N65 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSC4N65 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

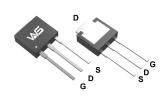
Product Summery

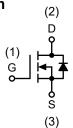
BV _{DSS}	R _{DSON}	I _D
650V	2600mΩ	4A

Applications

- AC/DC Power Conversion in Switched Mode Power Supplies (SMPS).
- Uninterruptible Power Supply(UPS)
- Adapter.

TO-251S-3L Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	650	V	
V_{GS}	Gate-Source Voltage	±30	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ^{1.5}	4	Α	
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ^{1.5}	2.5	А	
I _{DM}	Pulsed Drain Current ^{1.2.5}	16	Α	
EAS	Single Pulse Avalanche Energy ¹	128	mJ	
P _D	Total Power Dissipation ^{1,5}	77	W	
T _{STG}	Storage Temperature Range	-55 to 150	$^{\circ}$	
T_J	Operating Junction Temperature Range	-55 to 150	${\mathbb C}$	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient ¹		62.5	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		1.62	°C/W



Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	650			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =250uA		0.6		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =3.5A		2600	3000	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} . In =250uA	2.0	3.0	4.0	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS , IB -250UA		-4.57		mV/℃
	Drain Source Leakage Current	V _{DS} =650V , V _{GS} =0V , T _J =25℃			1	- uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =520V , V _{GS} =0V , T _J =55℃			10	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm30V$, V_{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =40V , I _D =3.5A		5		S
Qg	Total Gate Charge (10V)			10.2		
Q_{gs}	Gate-Source Charge	V _{DS} =520V , V _{GS} =10V , I _D =7A		2.3		nC
Q_{gd}	Gate-Drain Charge			2.1		
T _{d(on)}	Turn-On Delay Time			13		
Tr	Rise Time V _{DD} =300V , V _{GS} =10V ,			15.5		
T _{d(off)}	Turn-Off Delay Time	$R_G=25\Omega$, $I_D=10A$.		16		ns
T _f	Fall Time			40		
C _{iss}	Input Capacitance			550		
Coss	Output Capacitance V _{DS} =25V , V _{GS} =0V , f=1MHz			46		pF
C _{rss}	Reverse Transfer Capacitance			2.3		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,2,5}	V =V =0V Force Current			4	Α
I _{SM}	Pulsed Source Current ^{1,2}	V _G =V _D =0V , Force Current			16	Α
V_{SD}	Diode Forward Voltage ¹	V _{GS} =0V , I _S =7A , T _J =25℃			1.4	V
t _{rr}	Reverse Recovery Time			454		nS
Q _{rr}	Reverse Recovery Charge	IF=7A , dI/dt=40A/µs , T _J =25℃		2076		nC

Notes:

Note 1: limited by maximum junction temperature.

Note 2 : Bond wire current limit. Note 3 : V_{DS} =520V, I_{D} =4A.

Note 4 : $I_D=0.5A$, $V_{DD}=50V$, $T_j=25$ °C.

Note 5: Repetitive Rating: Pulse width limited by maximum junction temperature.



Typical Characteristics

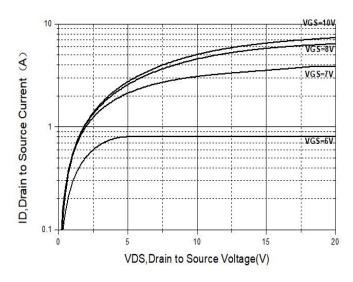


Figure 1 Output Characteristics

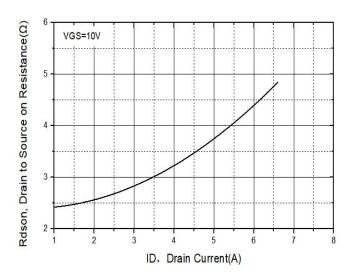


Figure 3 Rdson-ID Characteristics

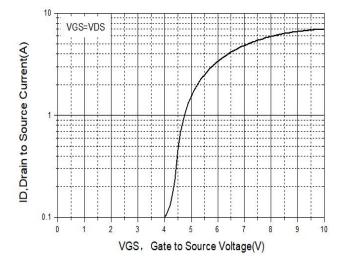


Figure 2 Transfer Characteristics

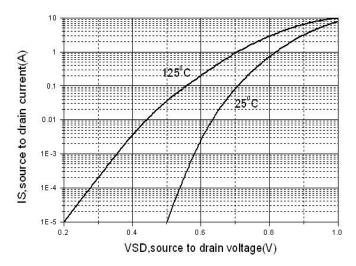


Figure 4 Body diode Characteristics



Typical Characteristics

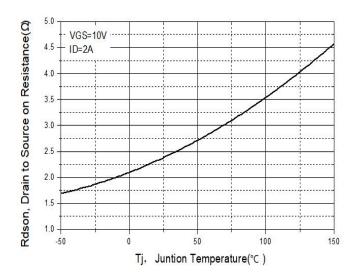


Figure 5 Rdson- T_J Relation

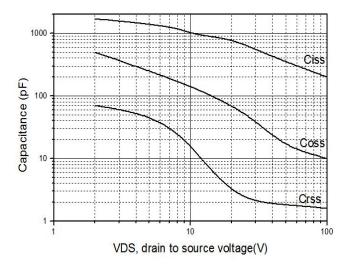


Figure 7 Capacitance vs V_{ds}

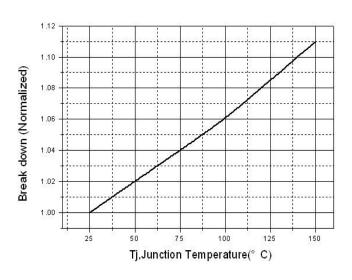


Figure 6 B_{VDSS} vs Junction Temperature

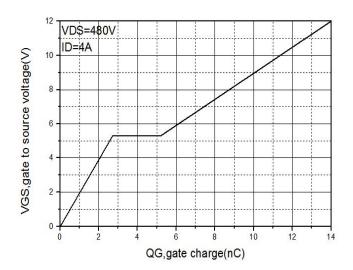
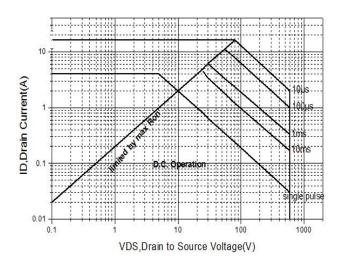


Figure 8 V_{GS} vs QG Characteristics



Typical Characteristics



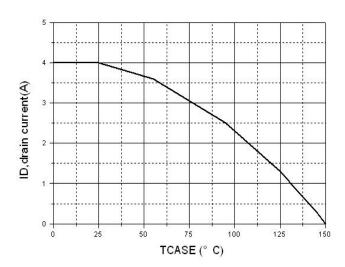


Figure 9 Safe Operation Area

Figure 10 Maximum current attenuation

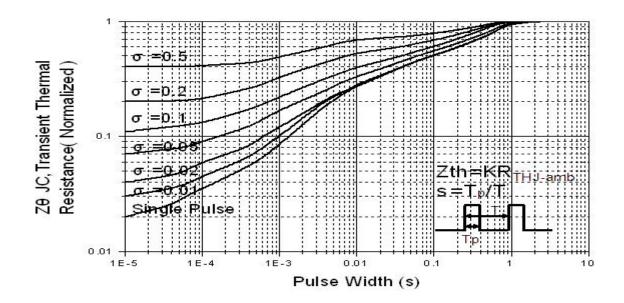
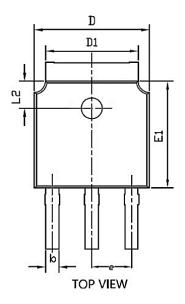
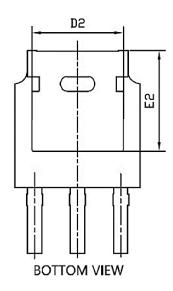


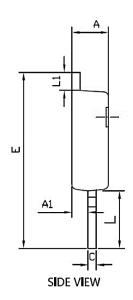
Figure 11 Normalized Maximum Transient Thermal Impedance



Packaging information







		Common				
Symbol	mm					
	Min	Тур	Max			
Α	2.2	2.3	2.4			
A1	0.9	1.0	1.1			
b	0.66	0.76	0.86			
С	0.46	0.52	0.58			
D	6.50	6.6	6.7			
D1	5.15	5.3	5.45			
D2	4.6	4.8	4.95			
E	10.4		11.5			
E1	6.0	6.1	6.2			
E2		5.400REF				
е	2.286BSC					
L	3.5	4.0	4.3			
L1	0.9		1.27			
L2	1.4		1.9			



Attention

- 1, Any and all Winsok power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your Winsok power representative nearest you before using any Winsok power products described or contained herein in such applications.
- 2, Winsok power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all Winsok power products described or contained herein.
- 3, Specifications of any and all Winsok power products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- 4, Winsok power Semiconductor CO., LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- 5,In the event that any or all Winsok power products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- 6, No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of Winsok power Semiconductor CO., LTD.
- 7, Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. Winsok power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- 8, Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the Winsok power product that you Intend to use.
- 9, this catalog provides information as of Sep.2014. Specifications and information herein are subject to change without notice.